TL3474, TL3474A HIGH-SLEW-RATE, SINGLE-SUPPLY OPERATIONAL AMPLIFIERS

SLVS461B - JANUARY 2003 - REVISED JULY 2003

- Low Offset . . . 3 mV (Max) for A-Grade
- Wide Gain-Bandwidth Product . . . 4 MHz
- High Slew Rate . . . 13 V/μs
- Fast Settling Time . . . 1.1 μs to 0.1%
- Wide-Range Single-Supply Operation ... 4 V to 36 V
- Wide Input Common-Mode Range Includes Ground (V_{CC})
- Low Total Harmonic Distortion . . . 0.02%
- Large-Capacitance Drive Capability
 ... 10,000 pF
- Output Short-Circuit Protection
- Alternative to MC33074/A and MC34074/A

description/ordering information

D, N, OR PW PACKAGE (TOP VIEW) 4OUT 10UT [1IN− ∏ 2 4IN-13 1IN+ 3 ∏ 4IN+ 12 Vcc+ 11 VCC_/GND 2IN+ [10 3IN+ 2IN- ∏ 6 9 | 3IN-20UT ∏ **30UT** 8

ORDERING INFORMATION

TA	V _{IO} max AT 25°C	PACKA	GE†	ORDERABLE PART NUMBER	TOP-SIDE MARKING	
		PDIP (N)	Tube of 25	TL3474ACN	TL3474ACN	
		0010 (D)	Tube of 50	TL3474ACD	TI 0.474.4	
	A-grade: 3 mV	SOIC (D)	Reel of 2500	TL3474ACDR	TL3474A	
0°C to 70°C	01117	T000D (DM)	Tube of 90	TL3474ACPW	T0.47.4A	
		TSSOP (PW)	Reel of 2000	TL3474ACPWR	T3474A	
		PDIP (N)	Tube of 25	TL3474CN	TL3474CN	
	Standard grade: 10 mV	0010 (D)	Tube of 50	TL3474CD	TI 2474C	
		SOIC (D)	Reel of 2500	TL3474CDR	TL3474C	
		TSSOD (D\A/)	Tube of 90	TL3474CPW	TI 0.474	
		TSSOP (PW)	Reel of 2000	TL3474CPWR	TL3474	
		PDIP (N)	PDIP (N) Tube of 25 TL3474AIN		Z3474A	
	l	0010 (D)	Tube of 50	TL3474AID	TI 0.47.4.4.1	
	A-grade: 3 mV	SOIC (D)	Reel of 2500	TL3474AIDR	TL3474AI	
	- O IIIV	T000D (DM)	Tube of 90	TL3474AIPW	70.47.44	
–40°C to 105°C		TSSOP (PW)	Reel of 2000	TL3474AIPWR	Z3474A	
-40°C to 105°C		PDIP (N)	Tube of 25	TL3474IN	TL3474IN	
		COIC (D)	Tube of 50	TL3474ID	TI 0.4741	
	Standard grade: 10 mV	SOIC (D)	Reel of 2500	TL3474IDR	TL3474I	
	10	TOCOD (DIA)	Tube of 90	TL3474IPW	70474	
		TSSOP (PW)	Reel of 2000	TL3474IPWR	Z3474	

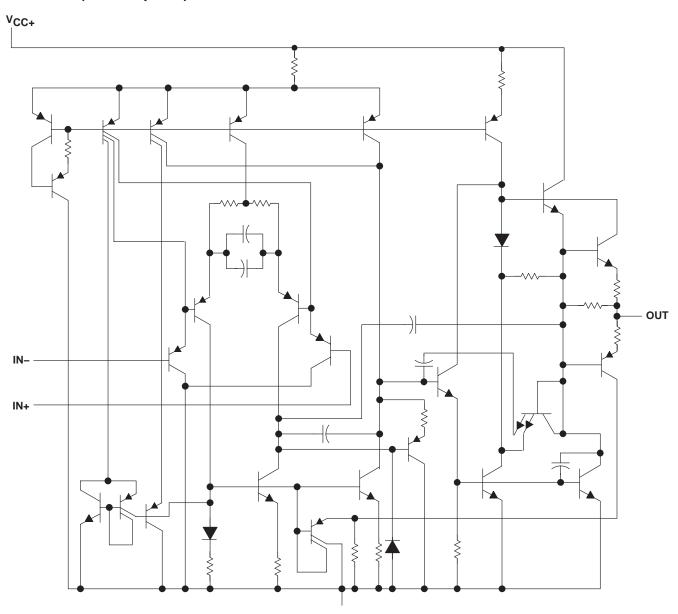
[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

SLVS461B - JANUARY 2003 - REVISED JULY 2003

description/ordering information (continued)

Quality, low-cost, bipolar fabrication with innovative design concepts is employed for the TL3474, TL3474A operational amplifiers. These devices offer 4 MHz of gain-bandwidth product, 13-V/ μ s slew rate, and fast settling time without the use of JFET device technology. Although the TL3474 and TL3474A can be operated from split supplies, they are particularly suited for single-supply operation because the common-mode input voltage range includes ground potential (V_{CC}). With a Darlington transistor input stage, these devices exhibit high input resistance, low input offset voltage, and high gain. The all-npn output stage, characterized by no dead-band crossover distortion and large output voltage swing, provides high-capacitance drive capability, excellent phase and gain margins, low open-loop high-frequency output impedance, and symmetrical source/sink ac frequency response. These low-cost amplifiers are an alternative to the MC34074/A and MC33074/A operational amplifiers.

schematic (each amplifier)



TL3474, TL3474A HIGH-SLEW-RATE, SINGLE-SUPPLY OPERATIONAL AMPLIFIERS

SLVS461B - JANUARY 2003 - REVISED JULY 2003

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage: V _{CC+} (see Note 1)	
V _{CC}	–18 V
Differential input voltage, V _{ID} (see Note 2)	±36 V
Input voltage, V _I (any input)	V _{CC±}
Input current, I _I (each input)	±1 mA
Output current, IO	
Total current into V _{CC+}	
Total current out of V _{CC}	
Duration of short-circuit current at (or below) 25°C (see Note 3)	
Package thermal impedance, θ _{JA} (see Notes 4 and 5): D package	86°C/W
N package	80°C/W
PW package	113°C/W
Operating virtual junction temperature, T _{.j.}	
Lead temperature 1.6 mm (1/16 inch) from case for 10 seconds	
Storage temperature range, T _{stg}	

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. All voltage values, except differential voltages, are with respect to the midpoint between V_{CC+} and V_{CC}_GND.
 - 2. Differential voltages are at the noninverting input with respect to the inverting input. Excessive input current can flow when the input is less than V_{CC} 0.3 V.
 - 3. The output can be shorted to either supply. Temperature and/or supply voltages must be limited to ensure that the maximum dissipation rating is not exceeded.
 - 4. Maximum power dissipation is a function of $T_J(max)$, θ_{JA} , and T_A . The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J(max) T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150°C can affect reliability.
 - 5. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions

			MIN	MAX	UNIT
VCC±	Supply voltage		4	36	V
.,	On any and the standard land	V _{CC} = 5 V	0	2.8	V
VIC	Common-mode input voltage	$V_{CC\pm} = \pm 15 \text{ V}$	-15	12.8	V
т.	One wating free air temperature	TL3474C, TL3474AC	0	70	°C
TA	Operating free-air temperature TL3474I, TL3474AI		-40	105	30

TL3474, TL3474A HIGH-SLEW-RATE, SINGLE-SUPPLY OPERATIONAL AMPLIFIERS

SLVS461B - JANUARY 2003 - REVISED JULY 2003

electrical characteristics at specified free-air temperature, $V_{CC\pm}$ = ± 15 V (unless otherwise noted)

					TL3474		1	ΓL3474A	1			
P	ARAMETER	TEST COND	ITIONS	TA	MIN	TYP [†]	MAX	MIN	TYP [†]	MAX	UNIT	
			V _C C = 5 V	25°C		1.5	10		1.5	3		
۷ _{IO}	Input offset voltage		V 145.V	25°C		1.0	10		1.0	3	mV	
	voltage		$V_{CC} = \pm 15 \text{ V}$	Full range‡			12			5		
α۷ιΟ	Temperature coefficient of input offset voltage	V _{IC} = 0, V _O = 0,	V _{CC} = ±15 V	Full range‡		10			10		μV/°C	
1	Input offset	$R_S = 50 \Omega$	V 145 V	25°C		6	75		6	75	~ ^	
liO	current		$V_{CC} = \pm 15 \text{ V}$	Full range [‡]			300			300	nA	
1	Input biog gurront		V 145 V	25°C		100	500		100	500	nA	
IВ	Input bias current		$V_{CC} = \pm 15 \text{ V}$	Full range‡			700			700	ΠA	
Common-mode		R _S = 50 Ω		25°C		–15 to 12.8			–15 to 12.8		V	
V _{ICR} input voltage range	NS = 30 22	Full range‡		–15 to 12.8			–15 to 12.8		V			
.,	High-level	$V_{CC+} = 5 \text{ V}, V_{CC-} = R_L = 2 \text{ k}\Omega$	25°C	3.7	4		3.7	4		,		
Vон	output voltage	R _L = 10 kΩ		25°C	13.6	14		13.6	14		V	
		$R_L = 2 k\Omega$		Full range‡	13.4			13.4				
.,	Low-level	$V_{CC+} = 5 \text{ V}, V_{CC-} = R_L = 2 \text{ k}\Omega$	25°C		0.1	0.3		0.1	0.3	.,		
VOL	output voltage	$R_L = 10 \text{ k}\Omega$		25°C		-14.7	-14.3		-14.7	-14.3	V	
		$R_L = 2 k\Omega$		Full range‡			-13.5			-13.5		
۸. ه	Large-signal differential	$V_0 = \pm 10 \text{ V, R}_1 = 2 \text{ J}$	kO	25°C	25	100		25	100		V/mV	
AVD	voltage amplification	VO = ±10 V, KL = 21	K22	Full range‡	20			20				
loo	Short-circuit	Source: V _{ID} = 1 V,		25°C	-10	-34		-10	-34		mA	
los	output current	Sink: $V_{ID} = -1 V$,	VO = 0	25 0	20	27		20	27		ША	
CMRR	Common-mode rejection ratio	$V_{IC} = V_{ICR}(min),$	$R_S = 50 \Omega$	25°C	65	97		80	97		dB	
ksvr	Supply-voltage rejection ratio (ΔV _{CC±} /ΔV _{IO})	$V_{CC\pm} = \pm 13.5 \text{ V to } \pm 13.5 \text{ V to } \pm 100 \Omega$:16.5 V,	25°C	70	97		70	97		dB	
		V _O = 0,	No load	25°C		3.5	4.5		3.5	4.5		
Icc	Supply current	ν _O = 0,	INU IUaU	Full range‡		4.5	5.5		4.5	5.5	mA	
.00	(per channel)	$V_{CC+} = 5 \text{ V}, V_{O} = 2 \text{ V}_{CC-} = 0, \text{ No load}$.5 V,	25°C		3.5	4.5		3.5	4.5	111/1	

 $[\]uparrow$ All typical values are at T_A = 25°C. ‡ Full range is 0°C to 70°C for the TL3474C, TL3474AC devices and -40°C to 105°C for the TL3474I, TL3474AI devices.

TL3474, TL3474A HIGH-SLEW-RATE, SINGLE-SUPPLY OPERATIONAL AMPLIFIERS

SLVS461B – JANUARY 2003 – REVISED JULY 2003

operating characteristics, $V_{CC\pm}$ = ± 15 V, T_A = $25^{\circ}C$

				TL3474		TL3474A			LINUT	
	PARAMETER	TEST CONDITION	ONS	MIN	TYP	MAX	MIN	TYP	MAX	UNIT
SR+	Positive slew rate	$V_{I} = -10 \text{ V to } 10 \text{ V},$	A _V = 1	8	10		8	10		.,,
SR-	Negative slew rate	$R_L = 2 k\Omega$, $C_L = 300 pF$	A _V = -1		13			13		V/μs
	Settling time	A 1 10 \/ atan	To 0.1%		1.1			1.1		
t _S	Settling time	$A_{VD} = -1$, 10-V step	To 0.01%		2.2			2.2		μs
Vn	Equivalent input noise voltage	f = 1 kHz,	$R_S = 100 \Omega$		49			49		nV/√ Hz
In	Equivalent input noise current	f = 1 kHz			0.22			0.22		pA/√ Hz
THD	Total harmonic distortion	$V_{O(PP)} = 2 \text{ V to } 20 \text{ V, R}_{L} = A_{VD} = 10, f = 10 \text{ kHz}$		0.02		0.02			%	
GBW	Gain-bandwidth product	f =100 kHz		3	4		3	4		MHz
BW	Power bandwidth	$V_{O(PP)} = 20 \text{ V}, R_L = 2 \text{ k}\Omega,$ $A_{VD} = 1, \text{ THD} = 5.0\%$			160			160		kHz
	Dharanana	$R_L = 2 k\Omega$,	C _L = 0	70			70			d
φm	Phase margin	$R_L = 2 k\Omega$,	$C_L = 300 \text{ pF}$		50			50		deg
	Onia manaia	$R_L = 2 k\Omega$,	C _L = 0		12			12		٩D
	Gain margin	$R_L = 2 k\Omega$,	C _L = 300 pF		4			4		dB
rį	Differential input resistance	VIC = 0			150			150		МΩ
Ci	Input capacitance	V _{IC} = 0			2.5			2.5		pF
	Channel separation	f = 10 kHz			101			101		dB
z ₀	Open-loop output impedance	f = 1 MHz,	A _V = 1		20			20		Ω

TYPICAL CHARACTERISTICS ($T_A = 25^{\circ}C$ UNLESS OTHERWISE NOTED)

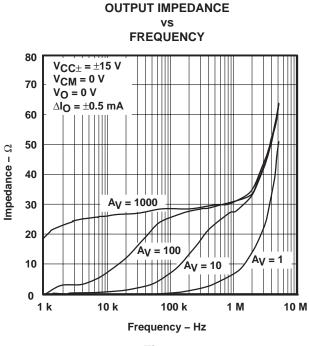


Figure 1

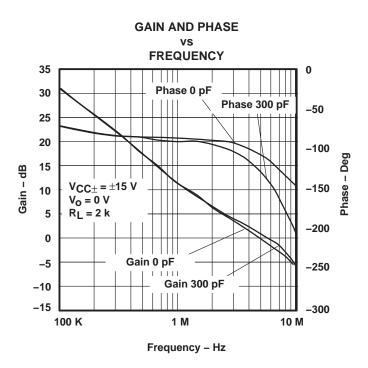
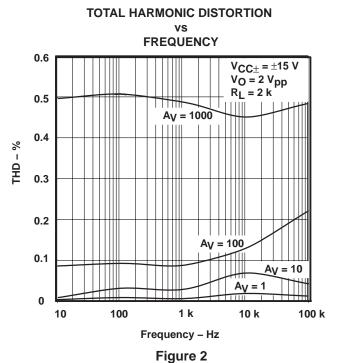


Figure 3



NORMALIZED INPUT BIAS CURRENT

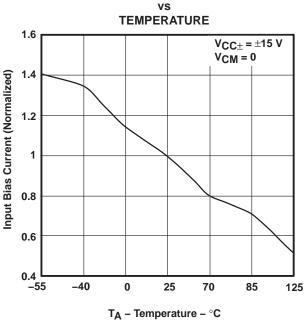


Figure 4

TYPICAL CHARACTERISTICS ($T_A = 25^{\circ}C$ UNLESS OTHERWISE NOTED)

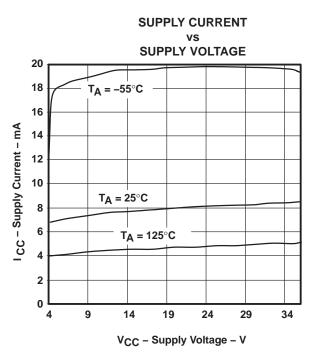


Figure 5

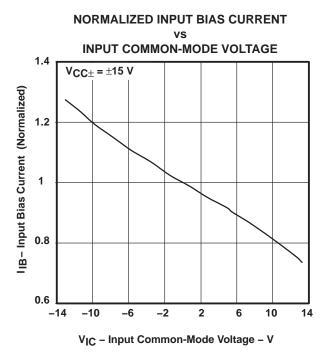


Figure 7

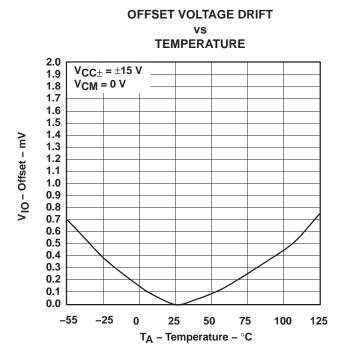


Figure 6

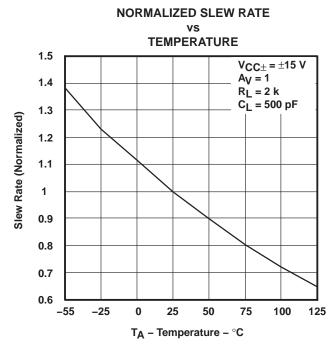


Figure 8

TYPICAL CHARACTERISTICS ($T_A = 25^{\circ}C$ UNLESS OTHERWISE NOTED)

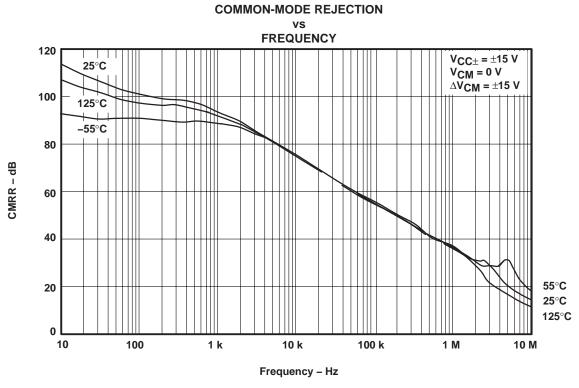


Figure 9

PACKAGE OPTION ADDENDUM

13-Aug-2021

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
TL3474ACD	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	TL3474A	Samples
TL3474ACDR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	TL3474A	Samples
TL3474ACN	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	TL3474ACN	Samples
TL3474ACPW	ACTIVE	TSSOP	PW	14	90	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	T3474A	Samples
TL3474ACPWR	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	T3474A	Samples
TL3474AID	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 105	TL3474AI	Samples
TL3474AIDR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 105	TL3474AI	Samples
TL3474AIDRE4	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 105	TL3474AI	Samples
TL3474AIN	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-40 to 105	TL3474AIN	Samples
TL3474AIPW	ACTIVE	TSSOP	PW	14	90	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 105	Z3474A	Samples
TL3474AIPWE4	ACTIVE	TSSOP	PW	14	90	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 105	Z3474A	Samples
TL3474AIPWR	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 105	Z3474A	Samples
TL3474CD	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	TL3474C	Samples
TL3474CDR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	TL3474C	Samples
TL3474CN	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	TL3474CN	Samples
TL3474CPW	ACTIVE	TSSOP	PW	14	90	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	T3474	Samples
TL3474CPWR	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	T3474	Samples
TL3474ID	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 105	TL3474I	Samples
TL3474IDR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 105	TL3474I	Samples
TL3474IN	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-40 to 105	TL3474IN	Samples

13-Aug-2021

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
TL3474IPW	ACTIVE	TSSOP	PW	14	90	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 105	Z3474	Samples
TL3474IPWR	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 105	Z3474	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

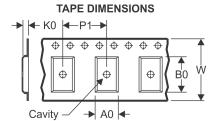
- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

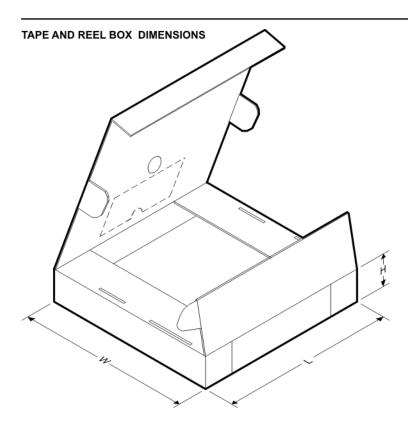


*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TL3474ACDR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
TL3474ACPWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
TL3474AIDR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
TL3474AIPWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
TL3474CDR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
TL3474CPWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
TL3474IDR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
TL3474IPWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

PACKAGE MATERIALS INFORMATION

23-Jul-2021

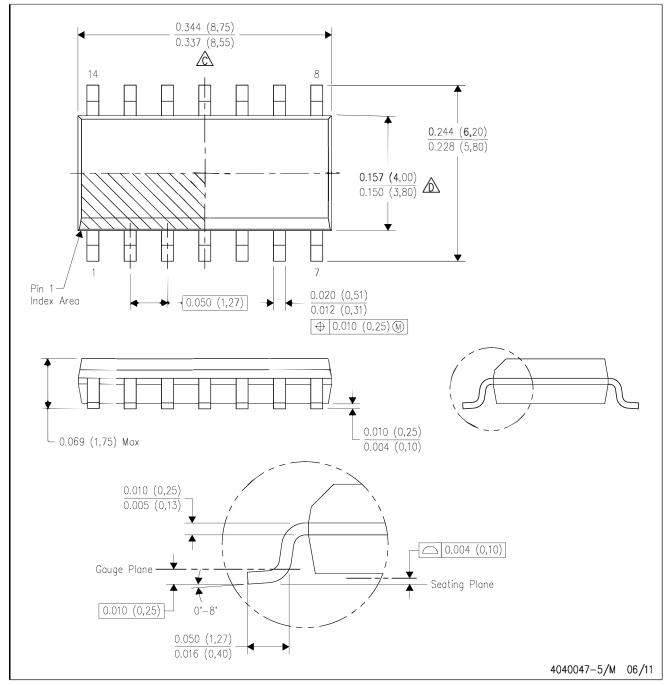


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TL3474ACDR	SOIC	D	14	2500	340.5	336.1	32.0
TL3474ACPWR	TSSOP	PW	14	2000	367.0	367.0	35.0
TL3474AIDR	SOIC	D	14	2500	340.5	336.1	32.0
TL3474AIPWR	TSSOP	PW	14	2000	853.0	449.0	35.0
TL3474CDR	SOIC	D	14	2500	340.5	336.1	32.0
TL3474CPWR	TSSOP	PW	14	2000	853.0	449.0	35.0
TL3474IDR	SOIC	D	14	2500	340.5	336.1	32.0
TL3474IPWR	TSSOP	PW	14	2000	853.0	449.0	35.0

D (R-PDS0-G14)

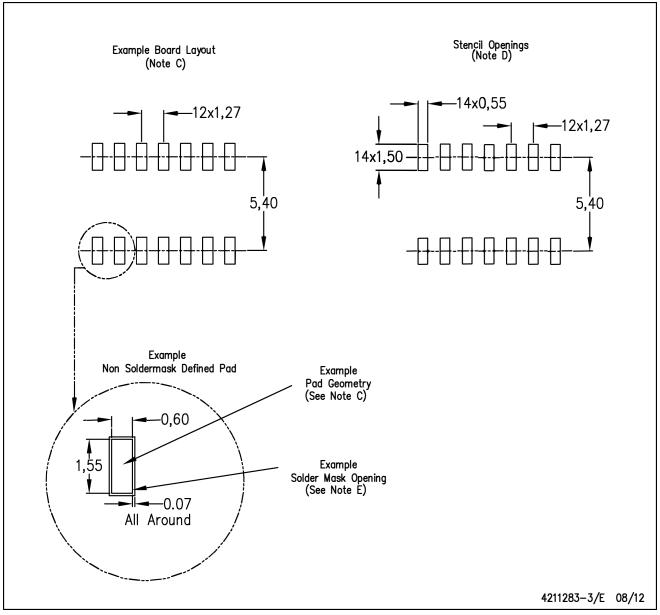
PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.

D (R-PDSO-G14)

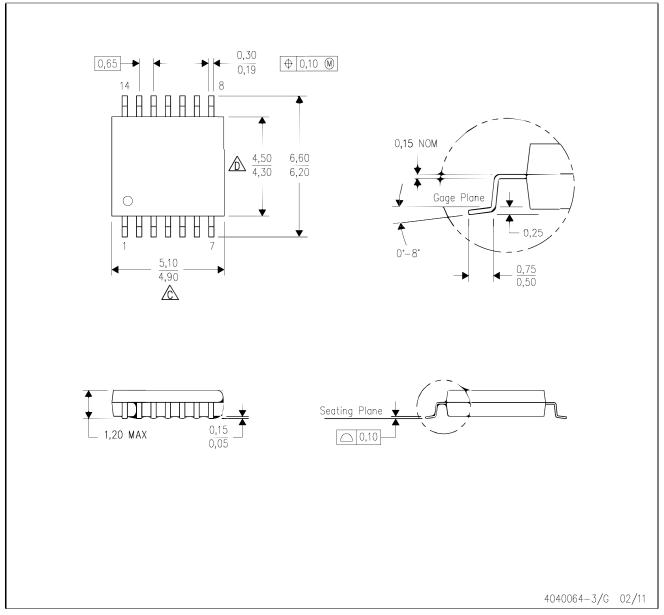
PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

PW (R-PDSO-G14)

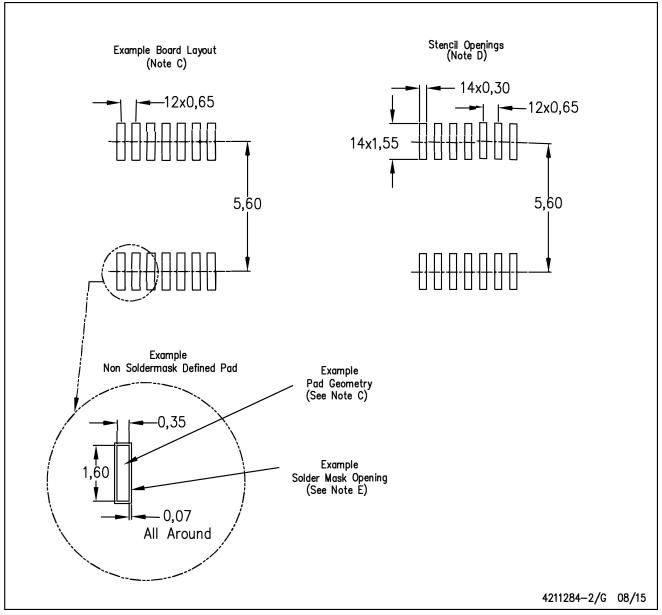
PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M—1994.
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
- E. Falls within JEDEC MO-153

PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE

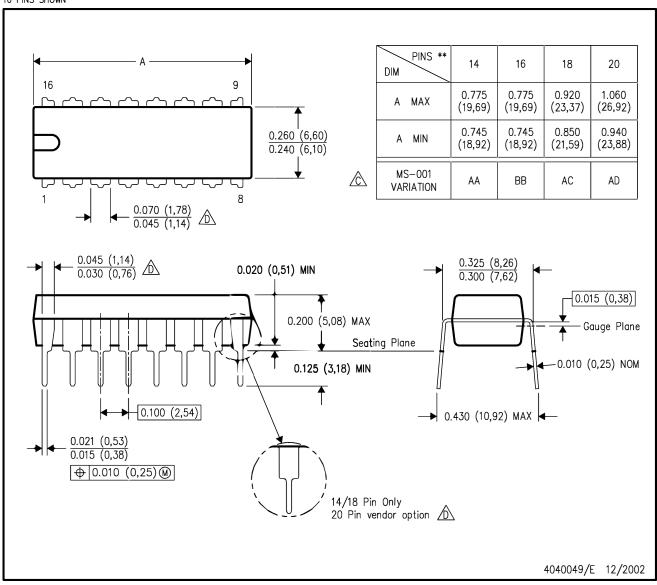


- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.